

(1.) <u>MAT'L:</u>

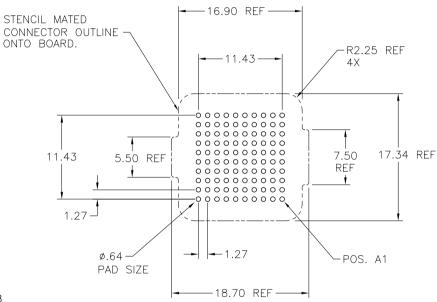
HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEET1) SOLDER BALL: (SEE TABLE ON SHEET1) EUTECTIC SnPb OR LEAD FREE 95.5Sn/4Aq/0.5Cu

- 2. OVERALL BOARD-TO-BOARD STACK HEIGHT WHEN MATED TO P/N 84513 100 POSITION 4.0mm RECPT. IS 4.0mm REF.
- 3. PLATING FOR -2XX SERIES DASH NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
- 4. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- (5) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



BOARD PATTERN

mat	mat'l. code						surface / tolerance					proje	projection product family										
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form: A4mmXLc

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PDM: Rev:D

**STATUS** Released

Printed: Oct 21, 2010

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